



## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(on)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C	
	12mΩ @ V <sub>GS</sub> = -10V	-10.5A	
-30V	21mΩ @ V <sub>GS</sub> = -4.5V	-8.0A	

# P-CHANNEL ENHANCEMENT MODE MOSFET

# Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

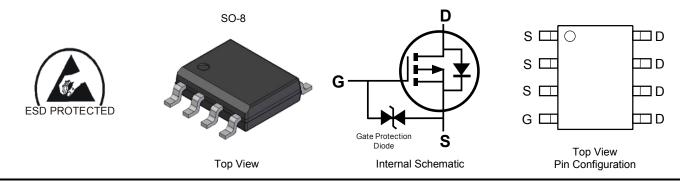
## **Description and Applications**

This MOSFET is designed to minimize the on-state resistance  $(R_{DS(on)})$  yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram Below
- Terminals: Finish Matte Tin Annealed Over Copper Lead Frame. Solderable per MIL-STD-202, Method 208 (C3)
- Weight: 0.074 grams (Approximate)



## Ordering Information (Note 4)

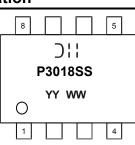
Part Number	Case	Packaging
DMP3018SSS-13	SO-8	2,500/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**



)|| = Manufacturer's Marking P3018SS = Product Type Marking Code YYWW = Date Code Marking YY or  $\overline{YY}$  = Year (ex: 21 = 2021) WW = Week (01 to 53)



### Maximum Ratings (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	-30	V
Gate-Source Voltage			V <sub>GSS</sub>	±25	V
Continuous Drain Current (Note 6) $V_{GS}$ = -10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	-10.5 -8.5	А
Continuous Drain Current (Note 6) $V_{GS}$ = -10V	Steady State	T <sub>C</sub> = +25°C T <sub>C</sub> = +70°C	ID	-25 -20	А
Maximum Continuous Body Diode Forward Current (Note 6)			Is	-20	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	-90	А
Avalanche Current (Note 7) L = 1mH			I <sub>AS</sub>	-14	А
Avalanche Energy (Note 7) L = 1mH			E <sub>AS</sub>	104	mJ

## Thermal Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	PD	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>0JA</sub>	101	°C/W
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	PD	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>0JA</sub>	73	°C/W
Total Power Dissipation (Note 6)		PD	10	W
Thermal Resistance, Junction to Case (Note 6)		R <sub>θJC</sub>	12.5	°C/W
Operating and Storage Temperature Range		TJ. TSTG	-55 to +150	°C

## Electrical Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

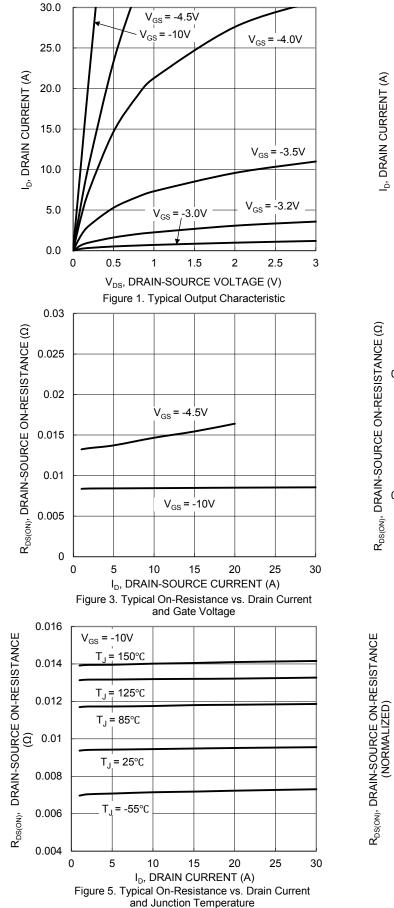
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	—		V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	_	-1	μA	$V_{DS}$ = -24V, $V_{GS}$ = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	—	_	±10	μA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)			-	-			
Gate Threshold Voltage	V <sub>GS(th)</sub>	-1.0		-3.0	V	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$	
Static Drain-Source On-Resistance	Dent		8.7	12	mΩ	V <sub>GS</sub> = -10V, I <sub>D</sub> = -11.5A	
	R <sub>DS(on)</sub>		14.5	21		$V_{GS}$ = -4.5V, I <sub>D</sub> = -8.5A	
Diode Forward Voltage	V <sub>SD</sub>	—	-0.7	-1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	2,147	_	pF		
Output Capacitance	Coss		407		pF	<sup>−</sup> V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, −f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		358		pF	1 – 1.0MHz	
Gate Resistance	R <sub>g</sub>	—	24	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = -5V)	Qg	—	28	_	nC		
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	—	51		nC		
Gate-Source Charge	Q <sub>gs</sub>	—	6.6	_	nC	V <sub>DS</sub> = -15V, I <sub>D</sub> = -11.5A	
Gate-Drain Charge	Q <sub>gd</sub>	—	15	_	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	—	7.8	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	19.9	_	ns	V <sub>DD</sub> = -15V, V <sub>GS</sub> = -10V,	
Turn-Off Delay Time	t <sub>D(off)</sub>	—	57.5	—	ns	R <sub>G</sub> = 6Ω, I <sub>D</sub> = -11.5A	
Turn-Off Fall Time	t <sub>F</sub>	—	42.8	_	ns	7	
Reverse Recovery Time	t <sub>RR</sub>	—	21.5	_	ns	44.54 11/11 4004/	
Reverse Recovery Charge	Q <sub>RR</sub>	_	11.6	_	nC	I <sub>S</sub> = -11.5A, dl/dt = 100A/μs	

Notes:

5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
7. I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.



## **DMP3018SSS**



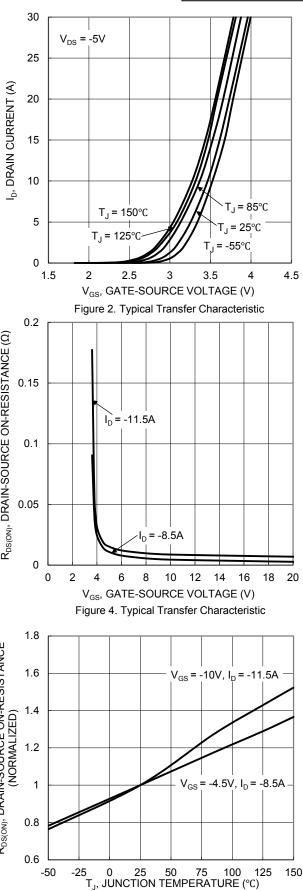


Figure 6. On-Resistance Variation with Junction Temperature



100

125

f = 1MHz

20

DC 

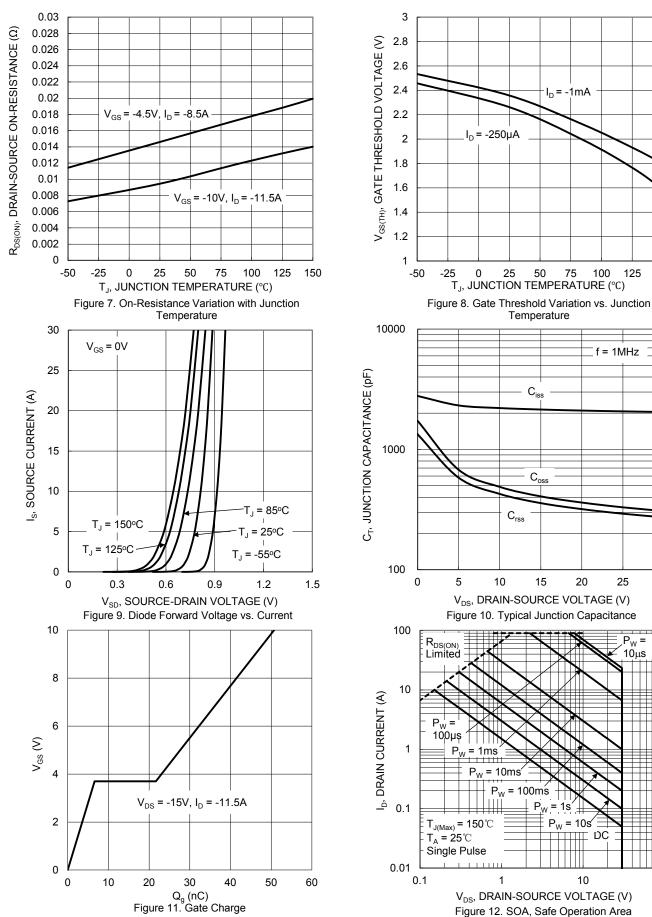
10

25

P<sub>w</sub> = 10µs

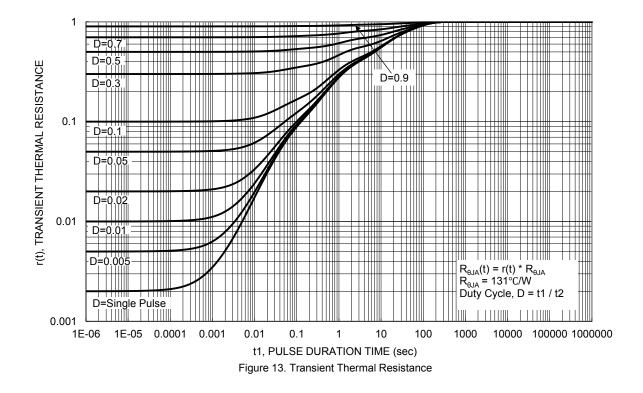
30

150



100

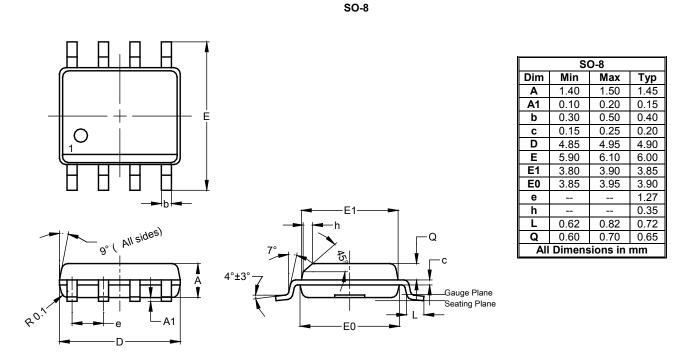






## **Package Outline Dimensions**

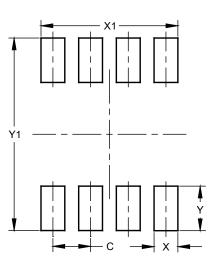
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8

## Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Ý	1.505
Y1	6.50



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